

COM-BT

Thermal Image Analysis Report

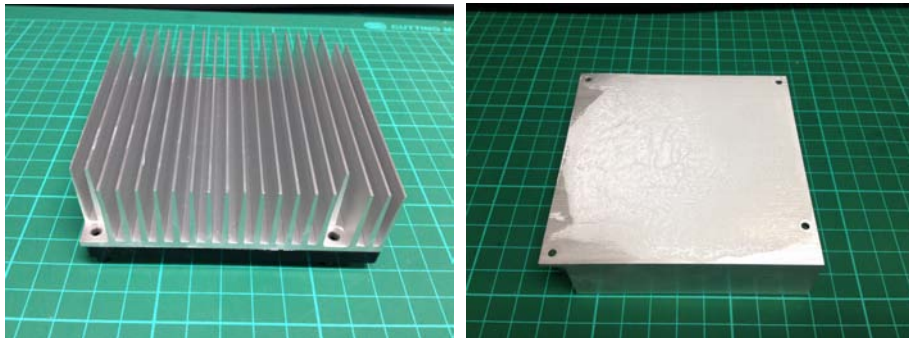
Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation <p style="text-align: center;">Comment: <u>Temperature at 1 component were estimated to be in marginal temperature point in comparion with component datasheets.</u></p>			
Test Result Summary				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date	Approval	Test Engineer
2014 / 08 / 14	Tom Lin	Jerry Chen

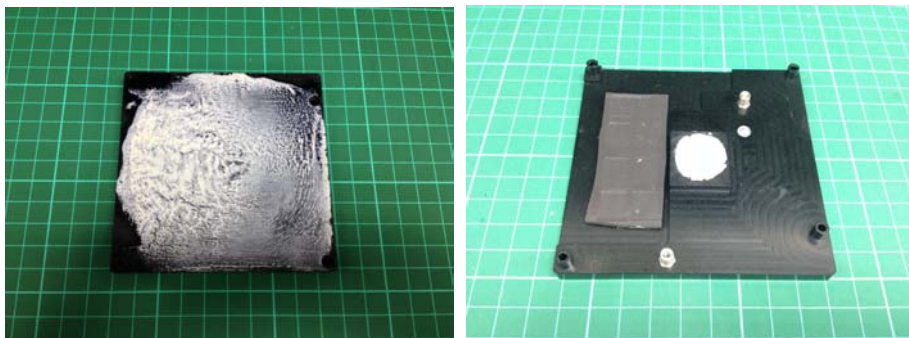
Sample Configuration & Quantity Under Test

- **Model name: COM-BT Rev. A0.3**
- **CPU: Intel Celeron J1900 1.99GHz**
- **BIOS: COM-BT R0.C (CMBTAMOC) (07/30/2014)**
- **Chipset: Intel Bay Trail SoC**
- **Memory: InnoDisk DDR3 1333 LV SO-DIMM 8GB / (Hynix / H5TC4G83AFR)*1**
- **2.5" SATA HDD: Toshiba / MK1676GSX 160GB**
- **Carrier Board: ECB-920A Rev. A0.3**
- **Test Software: Windows 8 / Run PassMark Burn In Test 7.1 Pro**
- **ATX Power Supply: CWT DSA400P-C**
- **Heat Sink / Heat-Spreader:**

Heat sink (P/N: M16CV00010)



Heat-Spreader (P/N: M16BT00000)



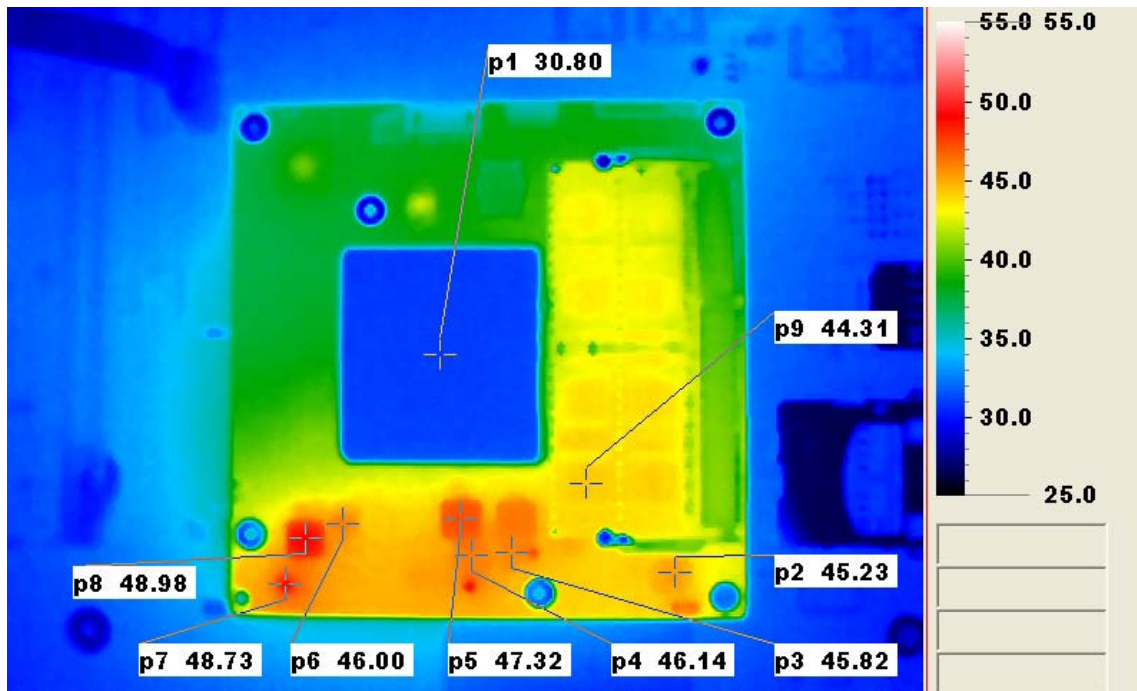
Thermal Image Analysis

1. Test Date: 2014-08-13
2. Test Product: COM-BT Rev. A0.3
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 40 Channel Thermal Recorder:
 - 4.1.1 YOKOGAWA Inc,
 - 4.2.2 Model: DA100-13-1D
Date of Calibration: 2013/10/01
Serial Number: 12A323190
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
Date of Calibration: 2014/01/06
Serial Number: 1051444
5. Test Condition:

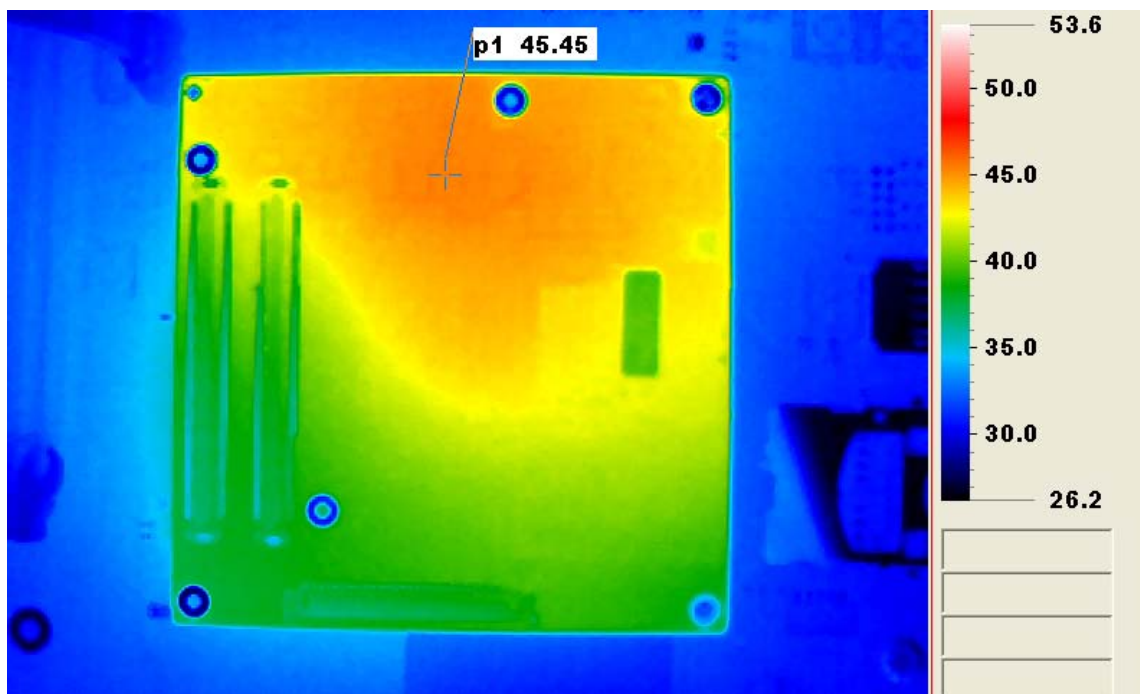
Test by DA-100: 25.0°C With Heat sink
6. Take Picture Time:

After power on 2 hours

**Temperature Profile Test:
Component Side:**

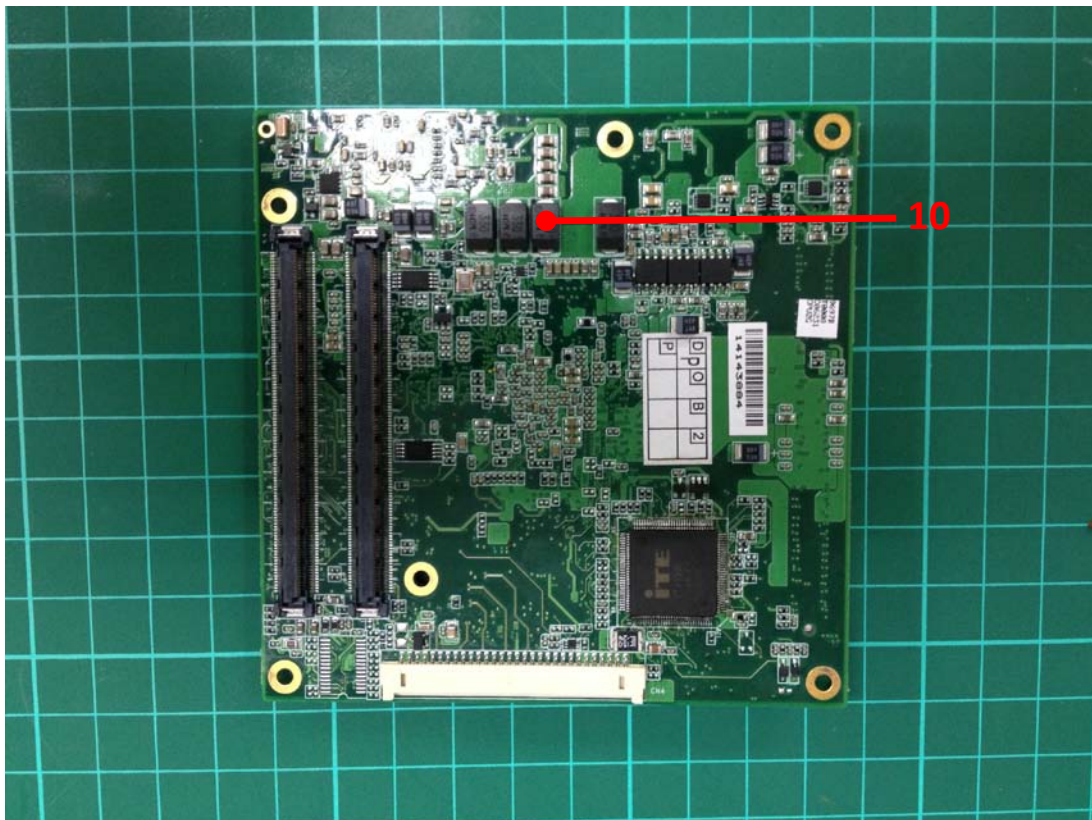
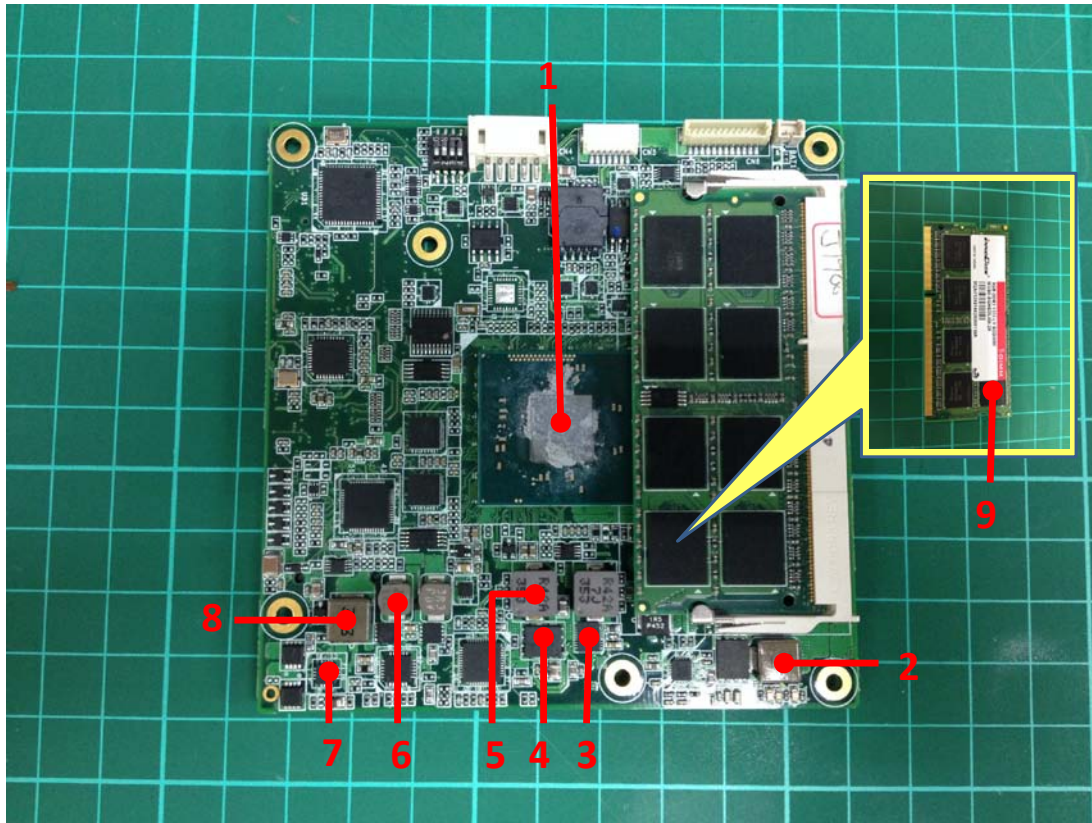


Back Side:



Terminal Recorder :

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.0°C	60°C	
1	U3	CPU - Intel Celeron CPU J1900 1.99GHz	105	48	83	
2	L1	(TF)COIL.1.5uH.GOTREND.GSTD6030PE-1R5M	140	49	84	
3	U59	(TF)IC.Synchronous Buck NexFETTM.SON 8P.TI.CSD97374Q4M	140	53.7	88.7	
4	Q36	(TF)PWR.DFN8 N-MOSFET.ON SEMI.NTMFD4901NFT1G	125	54.4	89.4	
5	L6	(TF)COIL.0.42uH.Panasonic.ETQP4LR42AFM	145	55.1	90.1	
6	L4	(TF)COIL.2.2uH.DCR=36.4mohm.NEC/TOKIN.MPLCG0530L2R2	135	53.8	88.8	
7	U56	(TF)IC.Synchronous Step-Down.QFN 16P.TI.TPS53219ARGTR	100	54.4	89.4	
8	L3	(TF)COIL.3.3uH.DCR=28mohm.GOTREND.GSTD6030PE-3R3M	140	56.4	91.4	
9	Memory	Innodisk DDR3L 1333 SO-DIMM 8G (Hynix / H5TC4G83AFR)	85	48.7	83.7	Note4
10	TC12	Battery - (TF)SP CAP.330uF.9mohmPanasonic.EEFSX0E331EY	120	50.7	85.7	
11	Air	Air Temperature	N/A	25	60	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.
3. **Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.
4. Defect NO. : [C130905QED10](#)